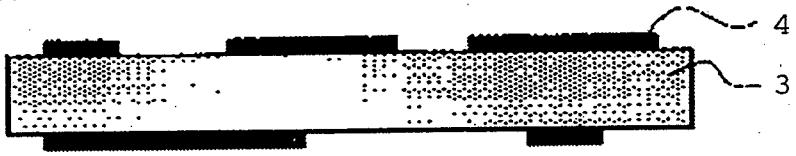
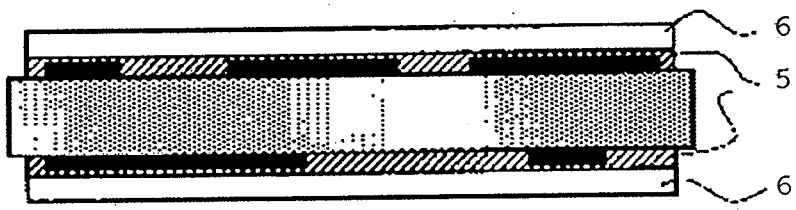
FIG. 3

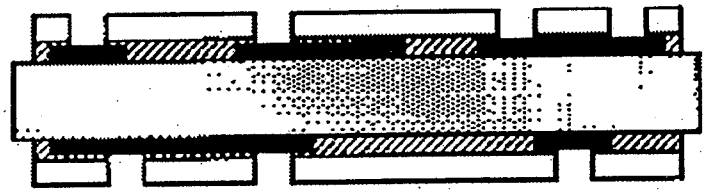
(a) core substrate



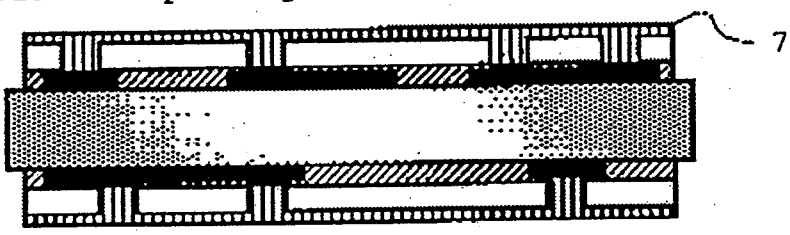
(b) first interlayer insulation layer formation



(c) via-hole perforation



(d) via fill plating



(e) first buildup layer pattern formation

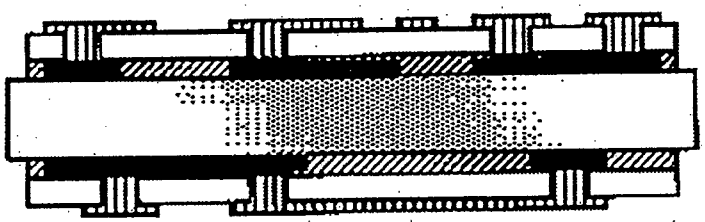
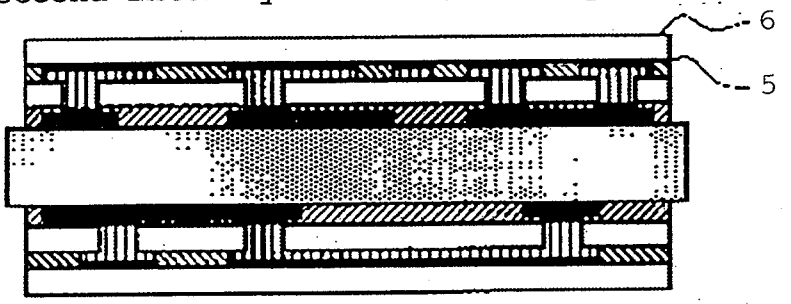
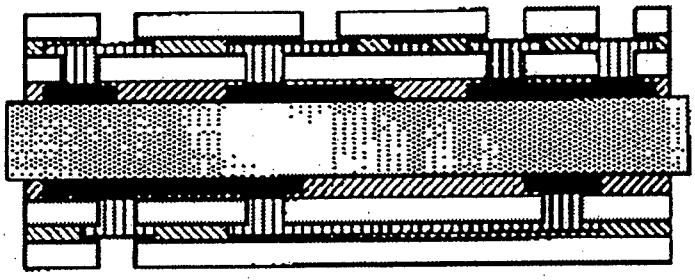


FIG. 4

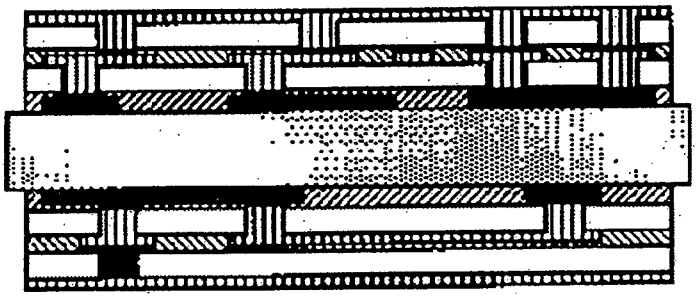
(e) second interlayer insulation layer formation



(b) via-hole perforation



(c) via fill plating



(d) second buildup layer pattern formation

